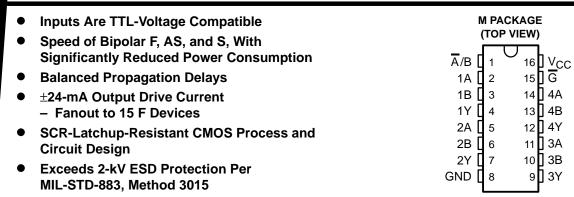
CD74ACT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

SCHS341 - MARCH 2003



description/ordering information

This quadruple 2-line to 1-line data selector/multiplexer is designed for 4.5-V to 5.5-V V_{CC} operation.

The CD74ACT158 features a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. This device provides inverted data.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC – M	Tape and reel	CD74ACT158M96	ACT158M

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each data selector/multiplexer)

	INPU	OUTPUT		
G	A/B	Α	В	Υ
Н	Х	Χ	Х	Н
L	L	L	Χ	Н
L	L	Н	X	L
L	Н	Χ	L	Н
L	Н	Χ	Н	L

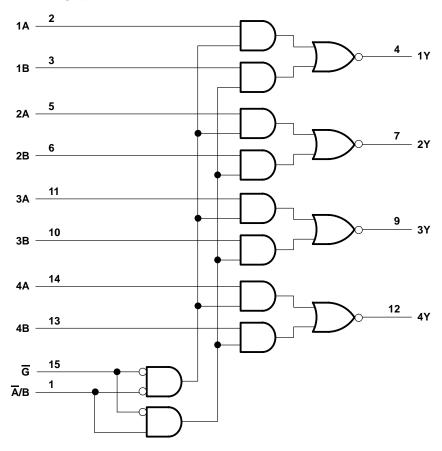


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I _{IK} (V _I < 0 V or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0 \text{ V or } V_O > V_{CC}$) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O > 0$ V or $V_O < V_{CC}$)	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2)	
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		T _A = 1	25°C	–55°C to 125°C		–40°C to 85°C		UNIT
		MIN MAX		MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	0	VCC	V
ІОН	High-level output current		-24		-24		-24	mA
loL	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT		
			MIN	MAX	MIN	MAX	MIN	MAX			
		ΙΟΗ = -50 μΑ	4.5 V	4.4		4.4		4.4			
V	\\. = \\ or \\.	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		v	
VOH	VI = VIH or VIL	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				V	
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85			
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1		
V		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	V	
VOL		I _{OL} = 50 mA [†]	5.5 V				1.65			\lnot $^{\vee}$ \mid	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
IĮ	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ	
Δl _{CC} ‡	$V_{I} = V_{CC} - 2.1 \text{ V}$		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A or B	0.37
G	0.83
Ā/B	1.33

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

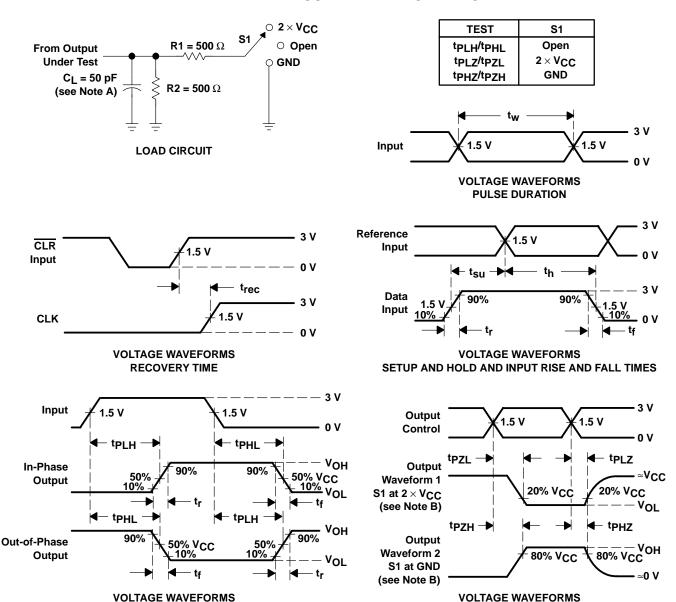
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°0 85°	UNIT	
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
^t PLH	A or B	D. Amir V				8.4	no
^t PHL	AUB	Any Y	2.3	9.2	2.4	8.4	ns
^t PLH	Ā/B	Anuv		13.5	3.6	12.3	nc
^t PHL	А/В	Any Y	3.4	13.5	3.6	12.3	ns
^t PLH	G	Any V	3.1	12.4	3.3	11.3	20
^t PHL	9	Any Y	3.1	12.4	3.3	11.3	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	149	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.

OUTPUT ENABLE AND DISABLE TIMES

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CD74ACT158M96	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT158M
CD74ACT158M96.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT158M

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT158M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CD74ACT158M96	SOIC	D	16	2500	340.5	336.1	32.0	

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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